

Radiation	Type	Technology	Case
Infrared	4 W	AlGaAs/GaAlAs	Plastic lens, metal case

	Outline: H = 12.4 mm (± 0.5) D = 16 mm (± 0.5) Thread M10 Pin 1 – cathode Pin 2 – anode	Description High-power infrared LED in an aluminium case with thread socket, for easy handling and heat sink mounting
	Applications Medical appliances, remote control and optical communications, light barriers, measurement systems	

Absolute Maximum Ratings

at $T_{amb} = 25^{\circ}\text{C}$, on heat sink ($S \geq 200 \text{ cm}^2$), unless otherwise specified

Parameter	Test conditions	Symbol	Value	Unit
DC forward current	on heat sink	I_F	1.1	A
Peak forward current	$t_p \leq 10 \mu\text{s}$, $f \leq 500 \text{ Hz}$	I_{FM}	2.0	A
Power dissipation	on heat sink	P	4	W
Operating temperature range	on heat sink	T_{amb}	-25 to +100	$^{\circ}\text{C}$
Storage temperature range	on heat sink	T_{stg}	-25 to +100	$^{\circ}\text{C}$
Junction temperature	on heat sink	T_j	100	$^{\circ}\text{C}$

Electrical Characteristics

$T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified

Parameter	Test conditions	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F = 350 \text{ mA}$	V_F		1.6	2.0	V
Forward voltage*	$I_F = 1000 \text{ mA}$	V_F		2.0	2.6	V
Switching time	$I_F = 350 \text{ mA}$	t_r, t_f		75		ns
Reverse voltage	$I_R = 100 \mu\text{A}$	V_R	5			
Thermal resistance junction-case		R_{thJC}		10		K/W

*only recommended on optimal heat sink

Optical Characteristics

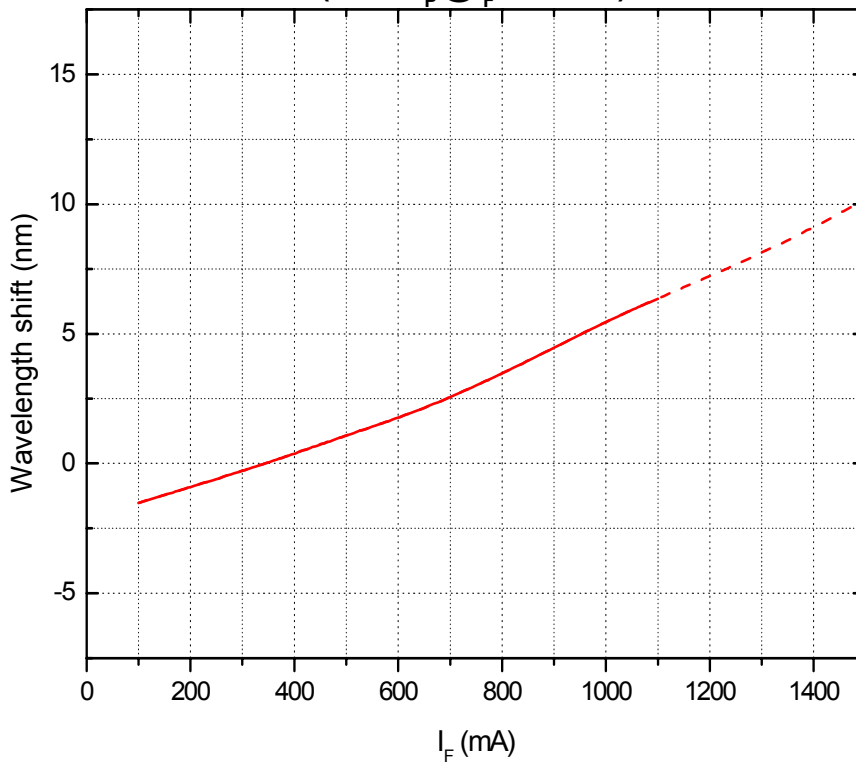
at $T_{amb} = 25^{\circ}C$, on heat sink ($S \geq 200 \text{ cm}^2$), unless otherwise specified

Parameter	Test conditions	Symbol	Min	Typ	Max	Unit
Radiant power	$I_F = 350 \text{ mA}$	Φ_e	40	55		mW
Radiant power*	$I_F = 1000 \text{ mA}$	Φ_e		150		mW
Radiant intensity	$I_F = 350 \text{ mA}$	I_e	100	190		mW/sr
Radiant intensity*	$I_F = 1000 \text{ mA}$	I_e		550		mW/sr
Peak wavelength	$I_F = 350 \text{ mA}$	λ_p	800	810	820	nm
Spectral bandwidth at 50%	$I_F = 350 \text{ mA}$	$\Delta\lambda_{0,5}$		30		nm
Viewing angle	$I_F = 350 \text{ mA}$	φ		35		deg

*only recommended on optimal heat sink

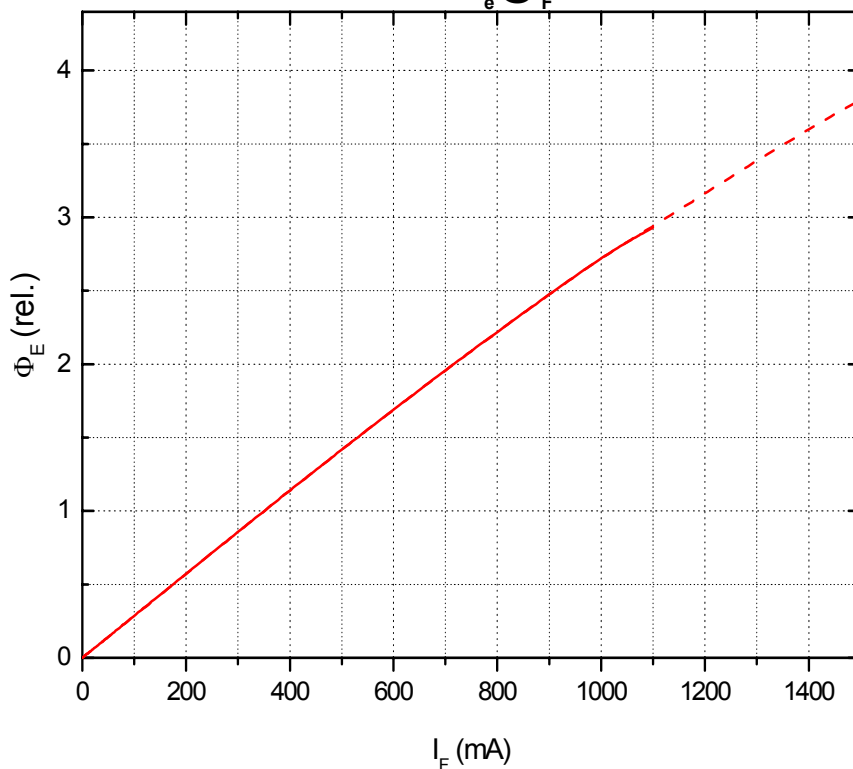
Note: All measurements carried out with *EPIGAP* equipment, on blank aluminium heat sink, $S = 180 \text{ cm}^2$, passive cooling. Measurement results and curve characteristics obtained with other heat sinks may differ.

Typical wavelength shift vs. forward current
(rel. to $\lambda_p @ I_F = 350 \text{ mA}$)

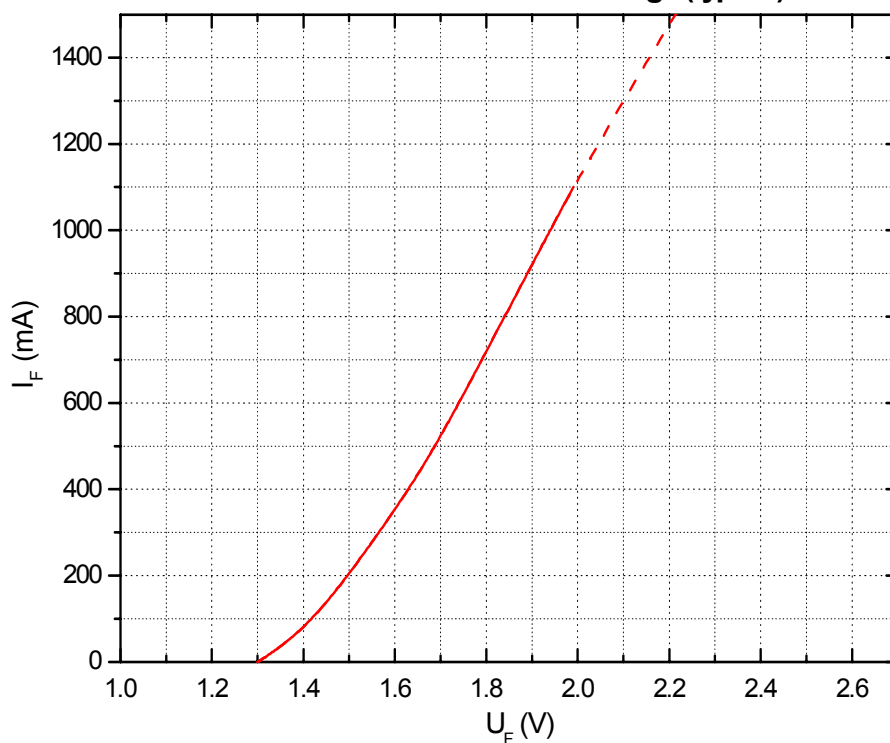


We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer.

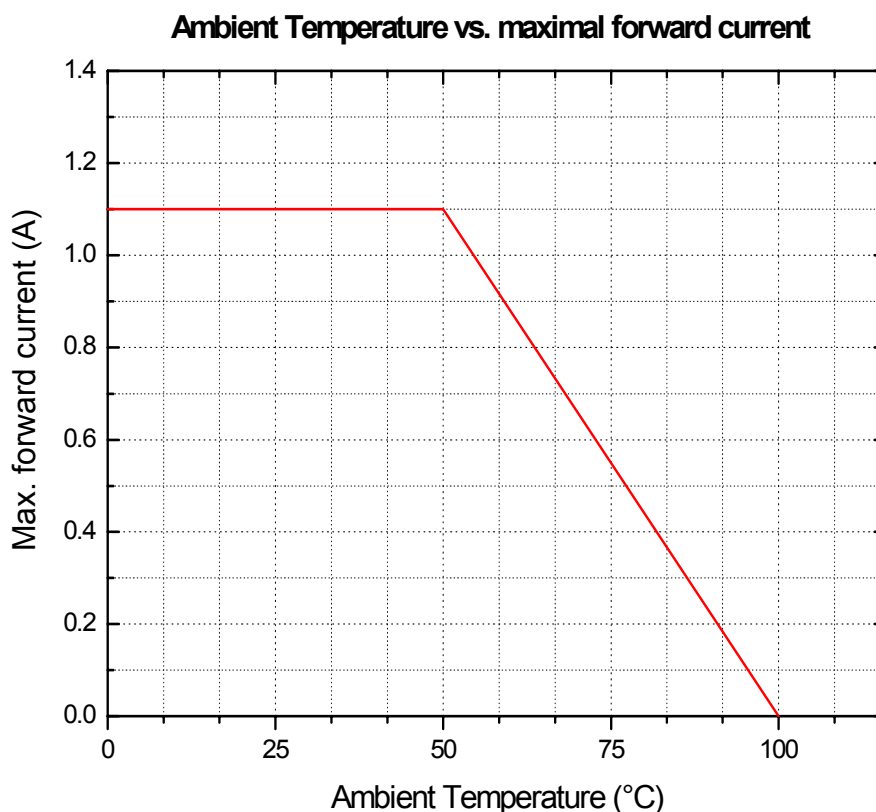
Radiant power vs. forward current (typical)
normalized to $\Phi_e @ I_F = 350 \text{ mA}$



Forward current vs. forward voltage (typical)



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Remarks concerning optical radiation safety*

At low forward current (<250 mA), and continuous operation, this LED may be classified as LED product *Class 1*, according to standard IEC 60825-1:A2. *Class 1* products are safe to eyes and skin under reasonably predictable conditions. This implicates a direct observation of the light beam by means of optical instruments.

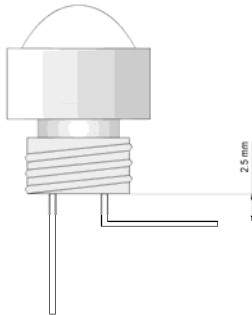
When driven with higher continuous forward current, (up to max. DC current), this product should be classified as LED product *Class 1M*, according to standard IEC 60825-1:A2. *Class 1M* products are safe to eyes and skin under normal conditions, including when users view the light beam directly. *Class 1M* products produce either a highly divergent beam or a large diameter beam. Therefore only a small part of the whole light beam can enter the eye. However, such optical products can be harmful to the retina if the beam is viewed using magnifying optical instruments. Therefore, users should not incorporate optics that could concentrate the output into the eyes.

*Note: Safety classification of an optical component mainly depends on the intended application and the way the component is being used. Furthermore, all statements made to classification are based on calculations and are only valid for this LED "as it is", and at continuous operation. Using pulsed current or altering the light beam with additional optics may lead to different safety classifications. Therefore these remarks should be taken as recommendation and guideline only.

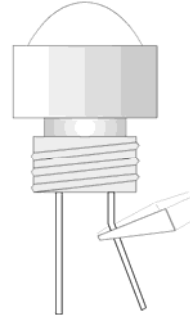
Handling precautions

To prevent damage to the LED during soldering and assembly, following precautions have to be taken into account.

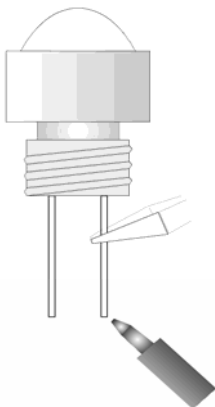
a) The bending point of the lead frame should be located at least 2.5 mm away from the body.



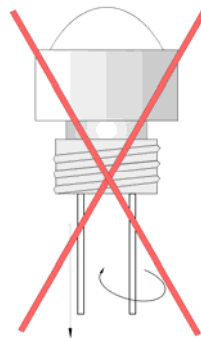
b) While bending, the base of the lead frame has to be fixed with radio pliers or similar.



c) To ensure an adequate strain relief, the lead frames have to be firmly fixed during soldering.



d) Avoid any torsion or tensile loading of the lead frames, especially when they have been heated after being soldered.



e) LEDs are static sensitive devices, so adequate handling precautions have to be taken, e.g. wearing grounding wrist straps.



ESD

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